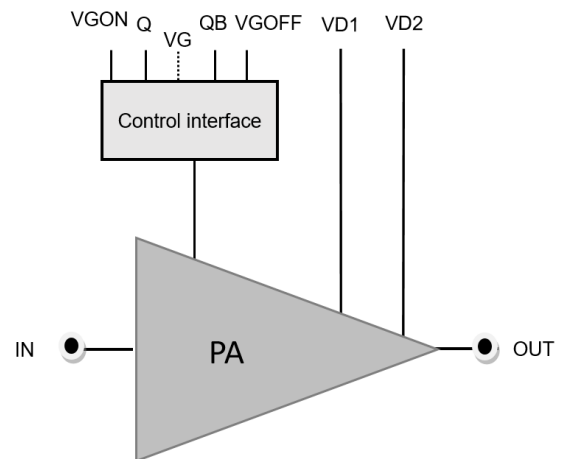


6-18 GHz Power Amplifier GaN Monolithic Microwave IC

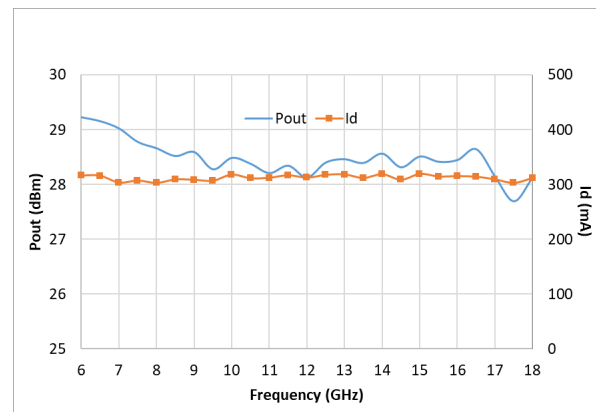
Description

The CHA5618-99F is a monolithic GaN Driver Amplifier in the frequency band 6-18GHz with a control interface for speed switching. This driver provides 28dBm of Output Power. The circuit exhibits a small signal gain of 22dB. The overall power supply is of 20V/150mA (quiescent current). It is designed for a wide range of applications, for military systems, such as electronic warfare, and test instrumentation. The part is manufactured on robust GaN HEMT technology and is available as a bare die.



Main Features

- Broadband performances: 6-18GHz
- Linear Gain = 22dB
- Pout = 28dBm for +12dBm Input Power
- Id associated current = 300mA
- DC bias: Vd=20V @Idq = 150mA
- 2.6x3.0mm²



Main Electrical Characteristics

Tcase = +25°C

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	6		18	GHz
Gain	Linear Gain		22		dB
Pout	Output Power @3dB comp. (Pin = 8dBm)		26		dBm
Psat	Output Power @saturation (Pin = 12dBm)		28		dBm
Id	Drain current @saturation (Pin = 12dBm)		300		mA

Specifications

Tcase = +25°C, Vd = +20V, Idq = 150mA

Symbol	Parameter	Min	Typ	Max	Unit
Freq	Frequency range	6		18	GHz
Gain	Linear Gain		22		dB
Pout	Output Power @3dB comp. (Pin = 8 dBm)		26		dBm
Psat	Output Power @saturation. (Pin = 12dBm)	28			
Id	Drain current @saturation. (Pin = 12 dBm)		300		mA
S11	Input return loss		-15		dB
S22	Output return loss		-15		dB
Idq	Quiescent current		150		mA
Vd	Drain voltage		20		V
Vg	Gate voltage		-2.7		V

These values are representative of measurements done in test fixture with a bonding wire of typically 0.25nH to 0.3nH.

Absolute Maximum Ratings ⁽¹⁾ ⁽²⁾

Tcase = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	27	V
Pin	Maximum peak input power overdrive	15	dBm

⁽¹⁾ Operation of this device above anyone of these parameters may cause permanent damage.

⁽²⁾ See Device thermal performances section page 5/20

Recommended Operating Range

Tcase = +25°C

Symbol	Parameter	Values	Unit
Vd	Drain bias voltage	20	V
Id	Drain bias current (no RF)	150	mA
Pin	Maximum peak input power overdrive	12	dBm
Tj	Maximum Junction temperature ⁽²⁾	200	°C

These values are representative of measurements done in test fixture with a bonding wire of typically 0.25nH to 0.3nH.

Temperature Range

Tcase	Operating temperature range	-40 to +85	°C
Tstg	Storage temperature range	-55 to +150	°C

Typical Bias Conditions

Two biasing procedures are available:

1. By using standard VG biasing
2. By using the control interface

Standard VG biasing

T_{case}=+25°C

Symbol	Pad N°	Parameter	Values	Unit
VG	17	Gate voltage tuned for I _{dq} ≈ 150mA	-2.7	V
VD1	13	1 st stage drain voltage	20	V
VD2	11	2 nd stage drain voltage	20	V

“Power ON” sequence

1. Bias PA gate voltage at VG close to V_{pinch-off} (Typically: V_g ≈ -5V)
2. Apply VD1 & VD2 bias voltage (Typically: VD = 20V)
3. Increase VG up to quiescent bias drain current I_{dq} (pulsed applied on the gate)
4. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias HPA gate voltage at VGON close to V_{pinch-off} (Typically: V_g ≈ -5V)
3. Turn VD1 & VD2 bias voltage to 0V
4. Turn VG bias voltage to 0V

Typical Bias Conditions

Control interface

T_{case}=+25°C

Symbol	Pad N°	Parameter	Values	Unit
VGON	19	Gate voltage tuned for Idq ≈ 150mA	≈-2.7	V
VGOFF	14	Gate pinch off voltage	-5	V
VD1	13	1 st stage drain voltage	20	V
VD2	11	2 nd stage drain voltage	20	V

Truth table

Driver State	Q	QB	VGON	VGOFF
Mode ON	-4V	-11V	≈-2.7V	-5V
Mode OFF	-11V	4V	≈-2.7V	-5V

“Power ON” sequence

1. PA gate voltage at VGON & VGOFF close to V_{pinch-off} (Typically: V_g ≈ -5V)
2. Bias PA gate voltage at QB = -11V
3. Bias PA gate voltage at Q = -4V
4. Apply VD1 & VD2 bias voltage (Typically: VD = 20V)
5. Increase VGON up to quiescent bias drain current Idq
6. Apply RF signal

“Power OFF” sequence

1. Turn off RF signal
2. Bias HPA gate voltage at VGON close to V_{pinch-off} (Typically: V_g ≈ -5V)
3. Turn VD1 & VD2 bias voltage to 0V
4. Turn VGON bias voltage to 0V
5. Turn VGOFF bias voltage to 0V
6. Turn Q & QB voltage to 0V

Device thermal performances

All the figures given in this section are obtained assuming that the die is only cooled down by conduction through the chip backside.

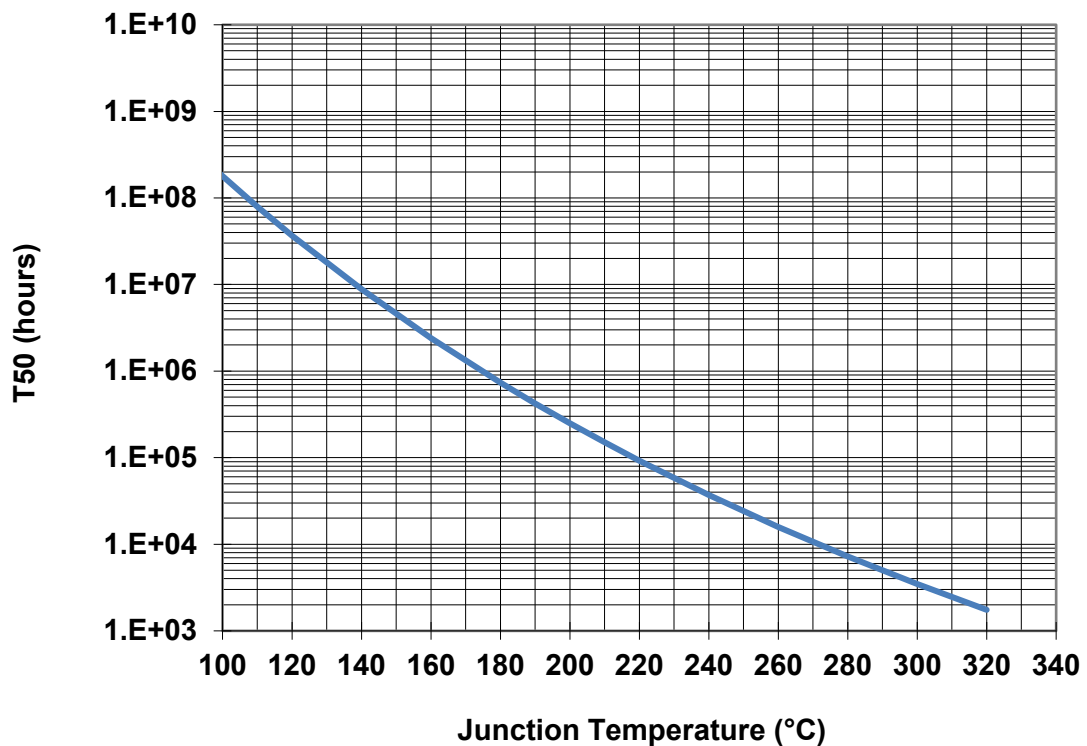
The temperature is monitored at the chip back-side interface (T_{backside}).

The system maximum temperature must be adjusted in order to guarantee that T_{junction} remains below the maximum value specified in the Absolute Maximum Ratings table.

So, the system PCB must be designed to comply with this requirement.

Parameter	Biasing conditions	T_{junction} (°C)	R_{TH} (°C/W)	T_{50} (hours)
$R_{\text{TH}}^{(1)}$ Thermal Resistance (Junction to Case)	$V_d = 20\text{V}$ $P_{\text{out}} = 28\text{dBm}$ $P_{\text{diss}} = 8\text{W}$	140	6.9	$1.9\text{E}+06$

¹ Assuming 85°C T_{case}



Typical On wafer measurements: Sij parameters

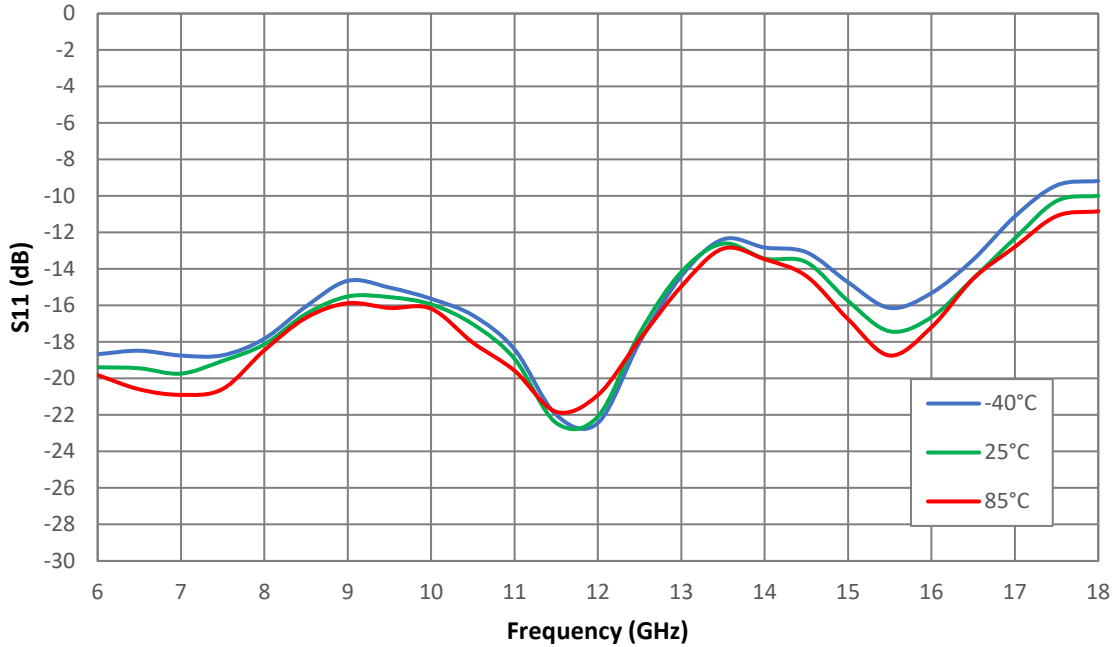
Tcase=+25°C, Vd = +20V, Id = 150mA

Freq (GHz)	S11 (dB)	PhS11 (°)	S12 (dB)	PhS12 (°)	S21 (dB)	PhS21 (°)	S22 (dB)	PhS22 (°)
6	-26.35	98.67	-56.40	-5.03	22.30	142.03	-7.94	-82.87
6.5	-28.19	101.23	-54.53	-26.76	22.29	118.85	-9.53	-91.72
7	-28.86	104.35	-54.13	-47.93	22.24	95.32	-11.73	-97.14
7.5	-28.60	108.45	-53.07	-72.01	22.27	72.85	-14.25	-95.47
8	-27.20	103.65	-52.17	-90.59	22.06	50.48	-16.27	-82.43
8.5	-25.40	96.48	-51.16	-111.99	22.10	28.37	-15.90	-65.43
9	-24.75	81.05	-50.64	-128.57	21.92	6.15	-14.17	-57.06
9.5	-23.51	67.34	-50.51	-150.34	21.86	-15.64	-12.38	-57.27
10	-23.02	52.24	-49.96	-170.72	21.80	-36.88	-10.96	-63.77
10.5	-22.47	38.80	-49.34	170.98	21.80	-58.66	-9.91	-70.33
11	-21.71	27.18	-48.33	153.12	21.82	-80.99	-9.33	-78.86
11.5	-21.35	14.00	-48.34	135.31	21.70	-103.17	-9.17	-88.15
12	-21.12	13.09	-47.23	117.07	21.83	-125.20	-9.19	-96.71
12.5	-19.78	8.65	-46.45	95.25	21.94	-149.28	-9.49	-107.32
13	-19.03	5.18	-45.68	70.41	21.86	-171.20	-10.17	-115.82
13.5	-17.41	3.94	-44.89	51.45	22.01	165.03	-11.10	-126.49
14	-15.88	0.79	-43.24	29.15	22.05	141.84	-12.83	-137.08
14.5	-14.49	-8.10	-42.59	3.56	22.00	117.07	-15.62	-141.32
15	-13.28	-12.28	-41.85	-20.19	21.76	93.24	-18.01	-143.78
15.5	-12.48	-21.08	-41.42	-46.87	21.69	66.73	-22.43	-117.27
16	-10.79	-25.58	-40.93	-69.27	21.52	42.44	-22.12	-87.81
16.5	-10.29	-33.07	-40.87	-95.80	21.42	15.79	-19.07	-64.72
17	-9.08	-41.45	-40.54	-116.34	21.13	-8.06	-15.98	-55.68
17.5	-8.30	-52.11	-39.80	-138.50	20.90	-32.31	-14.03	-58.63
18	-8.01	-63.62	-39.80	-156.14	20.89	-56.93	-12.57	-60.57

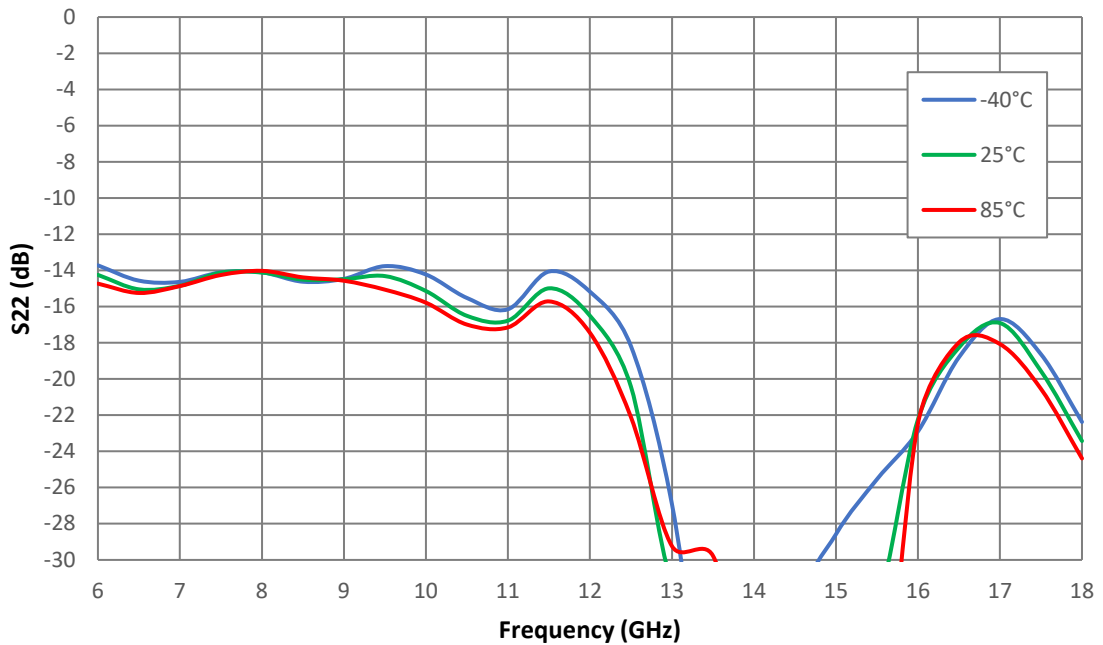
Typical Evaluation Board measurements

Tbackside = -40°C,+25°C & 85°C; Vd = 20V, Id = 150 mA @25°C

Input return loss S11 (dB) vs Frequency (GHz) with temperature variation



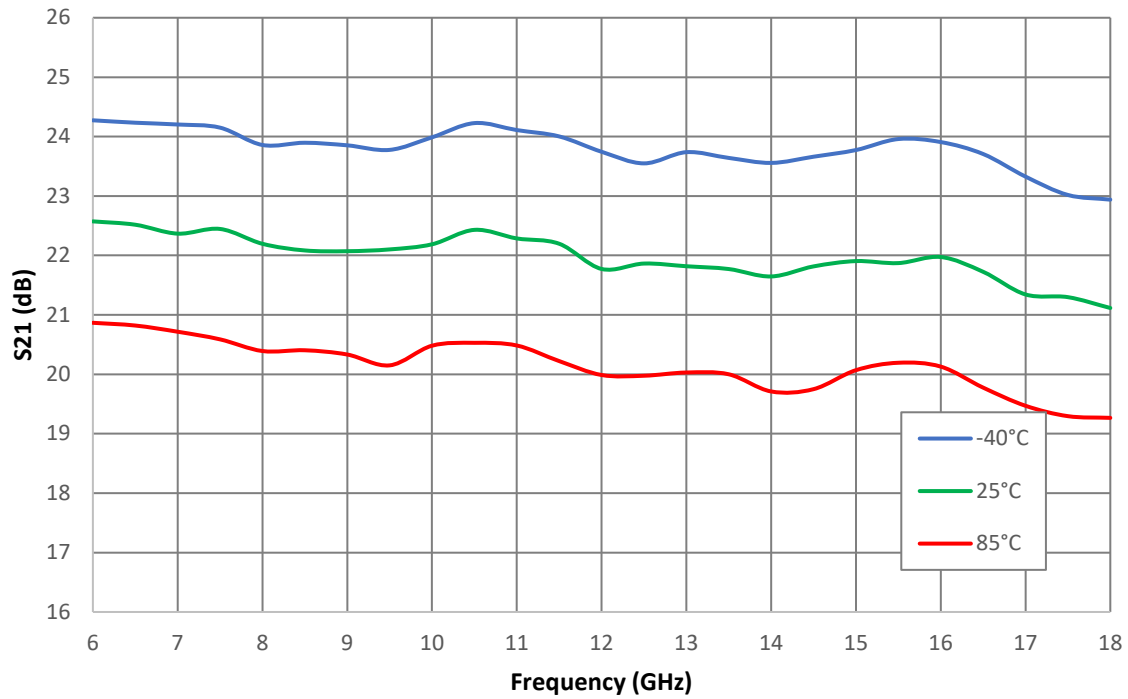
Output return loss S22 (dB) vs Frequency (GHz) with temperature variation



Typical Evaluation Board measurements

Tbackside = -40°C, +25°C & 85°C; Vd = +20, Id = 150 mA @ 25°C

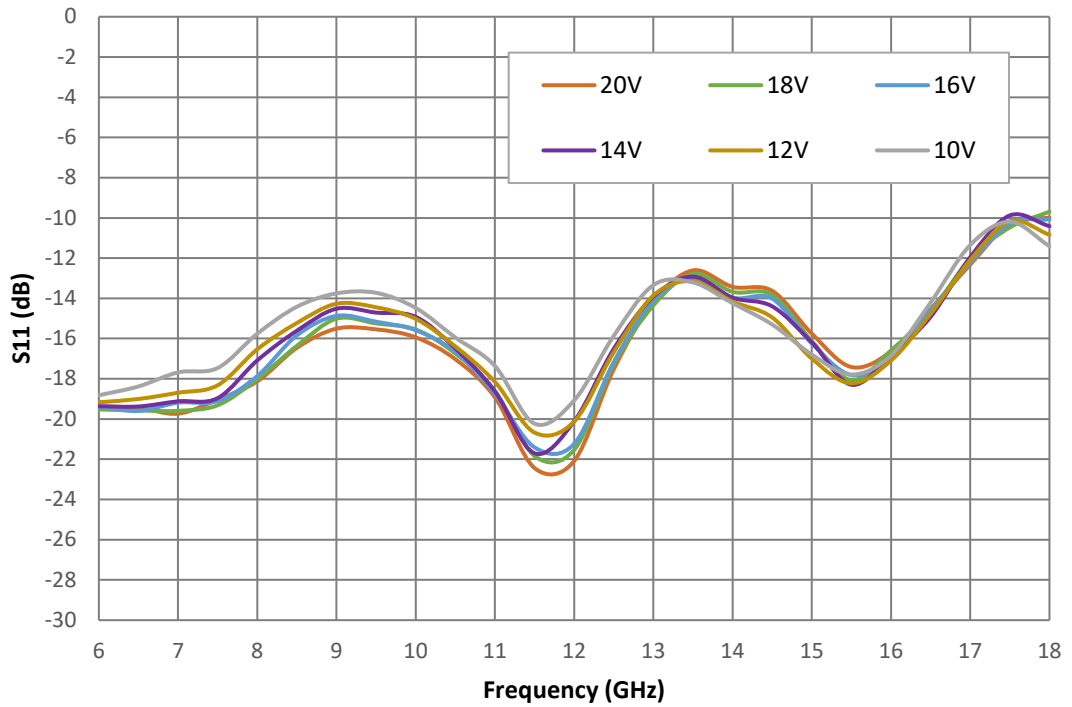
Linear gain S21 (dB) versus Frequency (GHz) with temperature variation



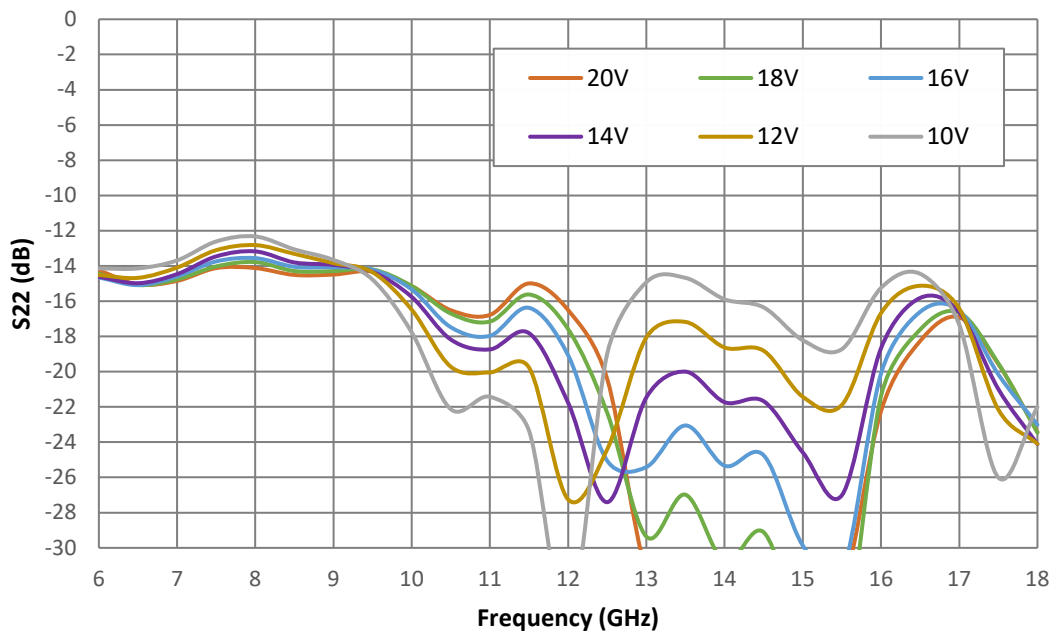
Typical Evaluation Board measurements:

Tbackside = +25°C ; Vd = 10, 12, 14, 16, 18 & 20V, Id = 150 mA

Input return loss S11 (dB) vs Frequency (GHz) with voltage variation



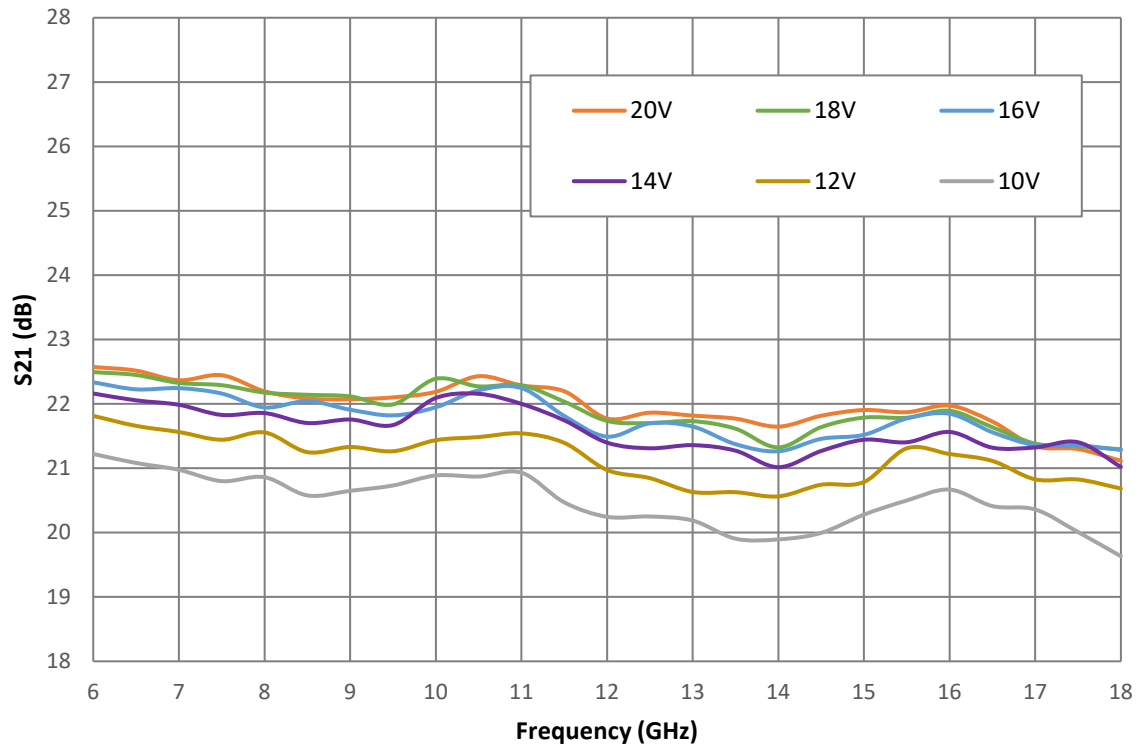
Output return loss S22 (dB) vs Frequency (GHz) with voltage variation



Typical Evaluation Board measurements

Tbackside = +25°C ; Vd = 10, 12, 14, 16, 18 & 20V, Id = 150 mA

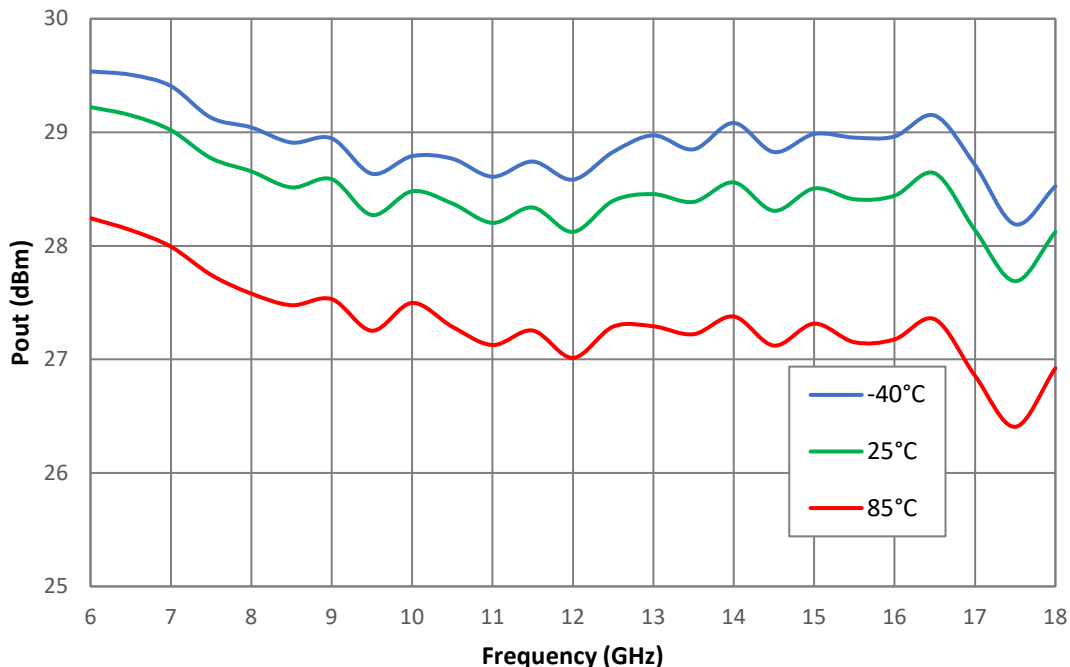
Linear gain S21 (dB) vs Frequency (GHz) with voltage variation



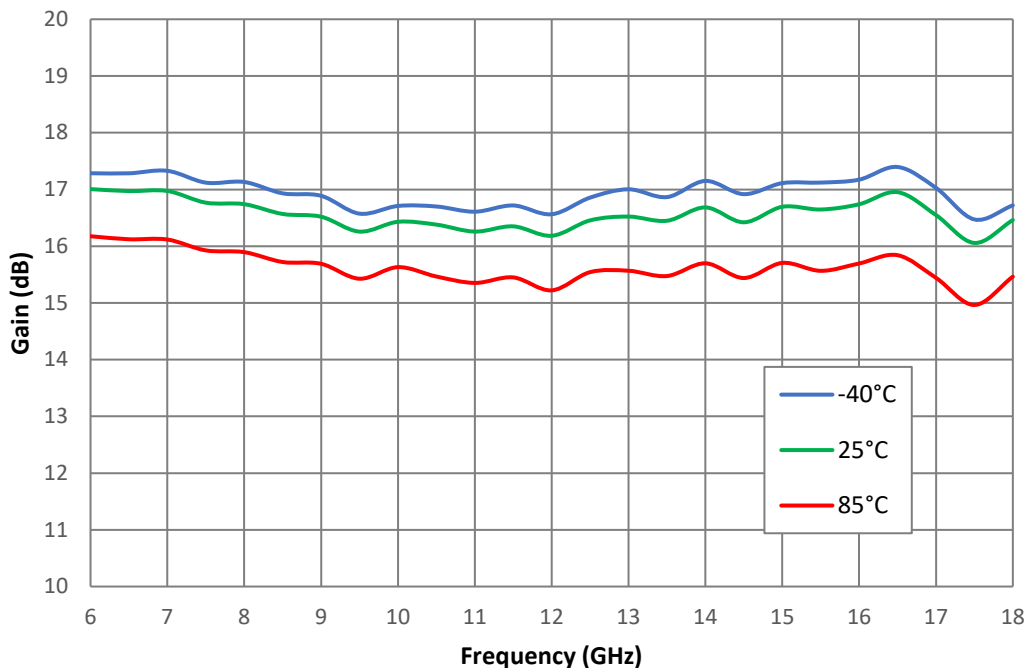
Typical Evaluation Board measurements

Tbackside = -40°C, +25°C & +85°C, Vd = +20V, Id = 150 mA@ 25°C; Pin = 12dBm

Pout (dBm) vs Frequency (GHz) with temperature variation



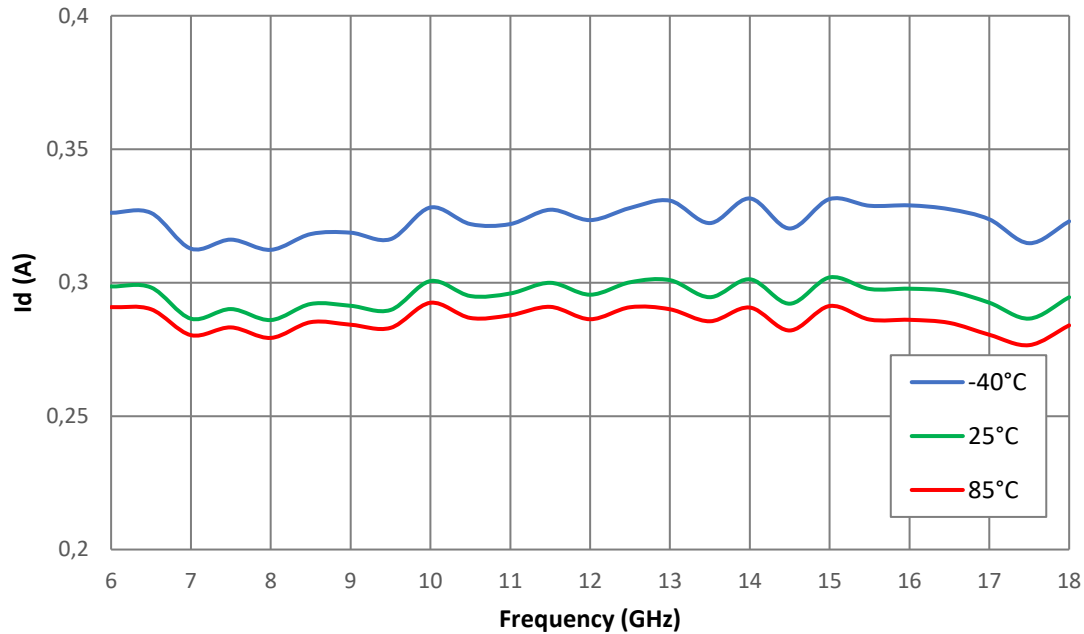
Gain (dB) versus Frequency (GHz) with temperature variation



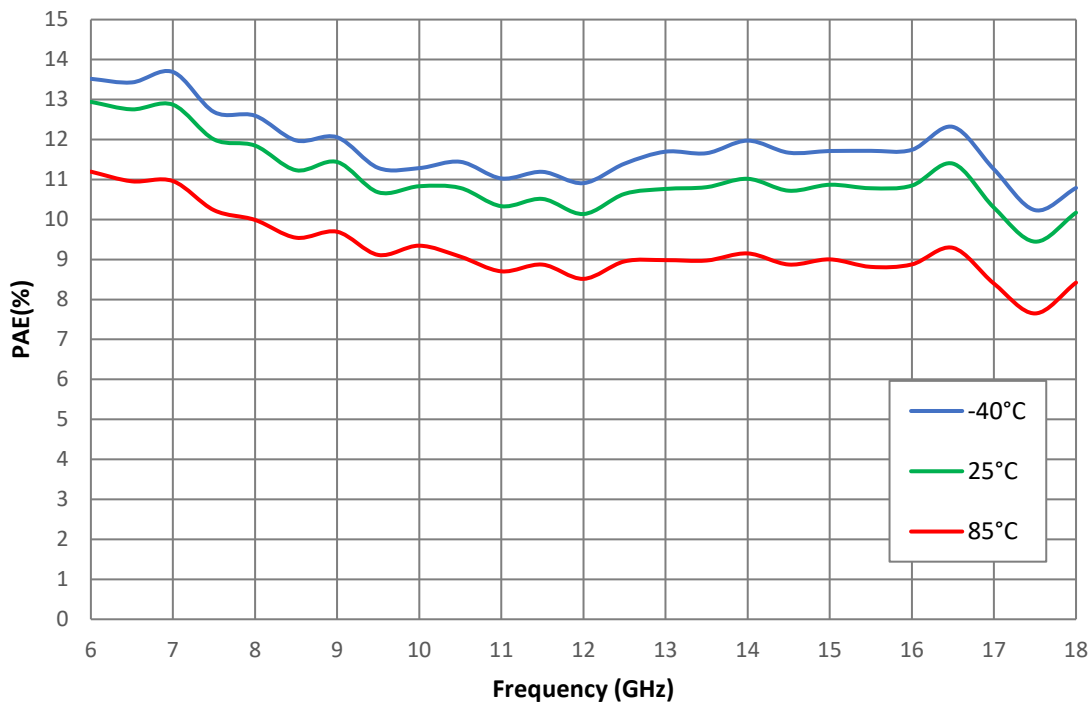
Typical Evaluation Board measurements

Tbackside = -40°C, +25°C & +85°C, Vd = +20V, Id = 150 mA @25°C; Pin = 12dBm

Id (A) versus Frequency (GHz) with temperature variation



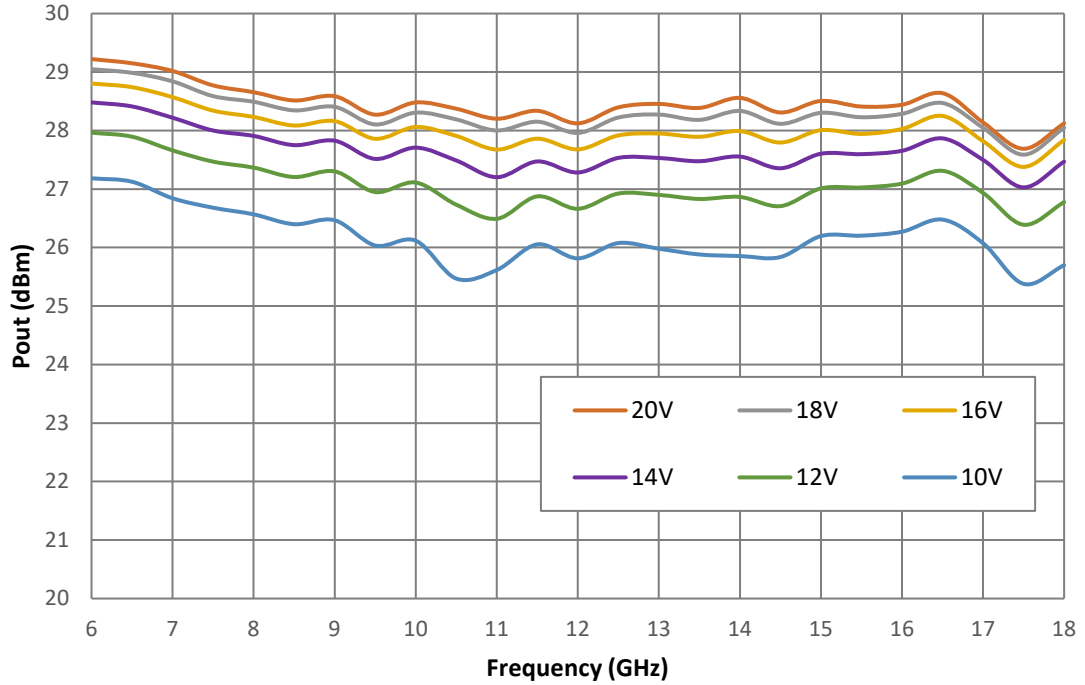
PAE (%) versus Frequency (GHz) with temperature variation



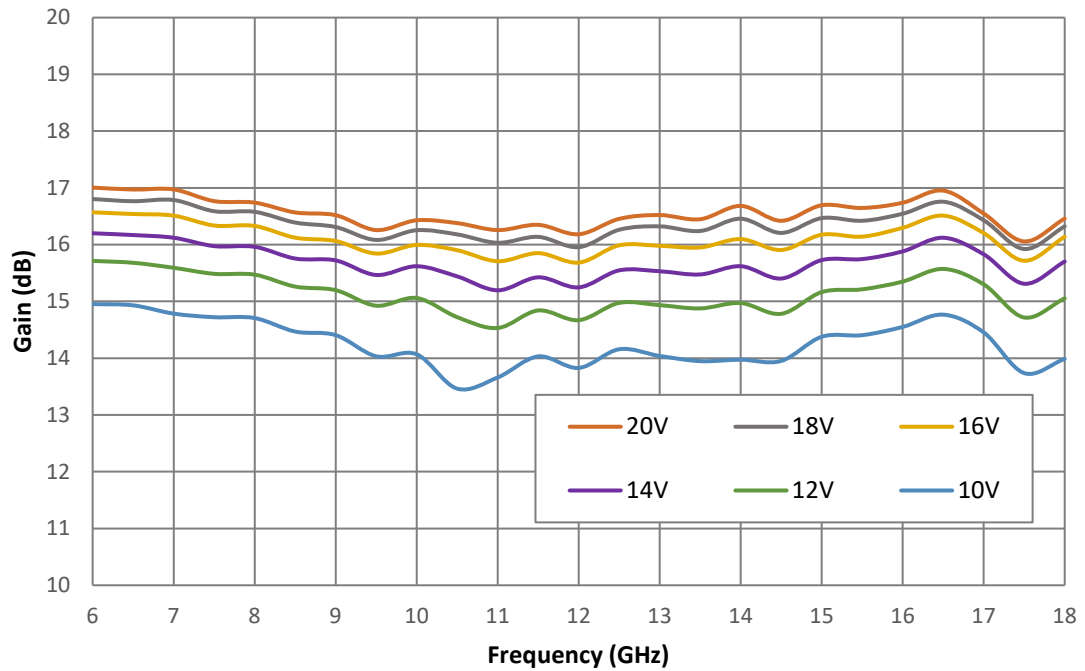
Typical Evaluation Board measurements

Tbackside = 25°C, Vd = 10, 12, 14, 16, 18 & 20V, Id = 150 mA; Pin = 12 dBm

Pout (dBm) versus Frequency (GHz) with voltage variation



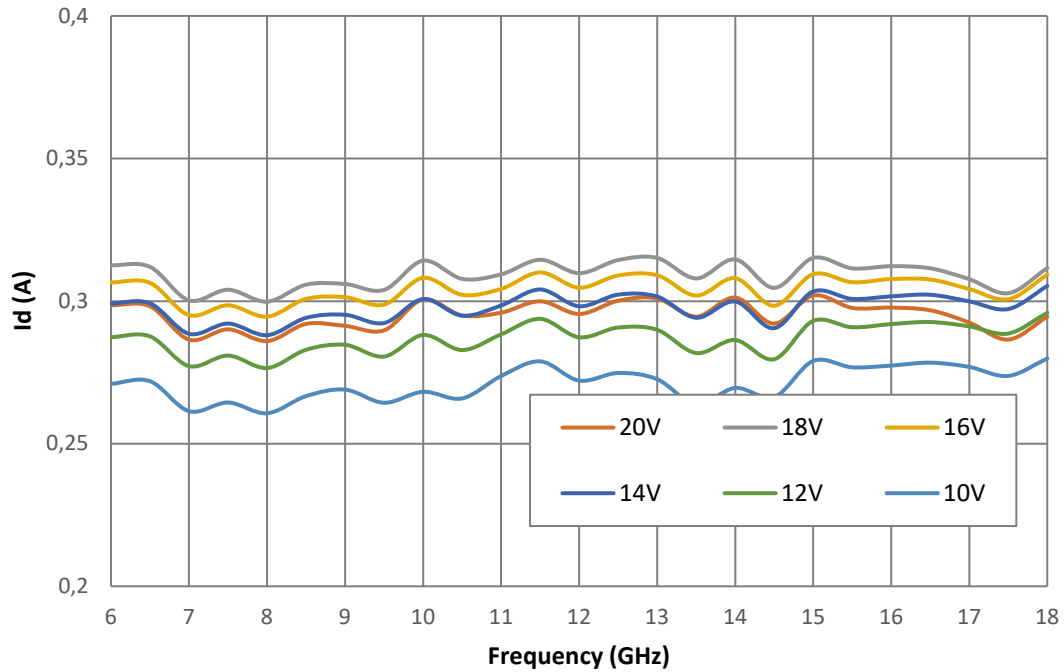
Gain (dB) versus Frequency (GHz) with voltage variation



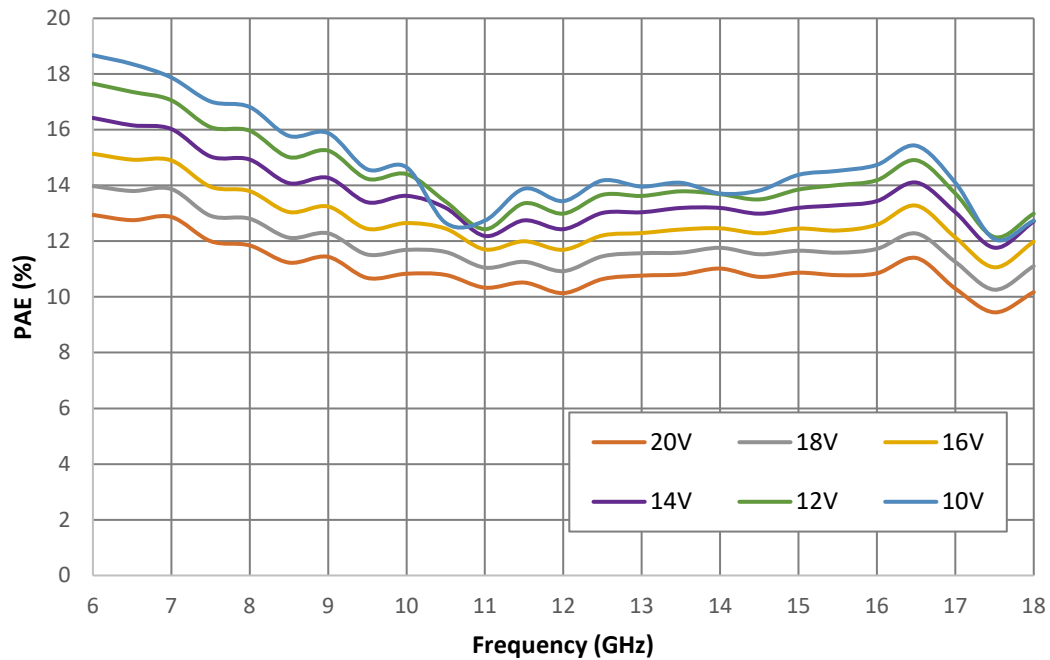
Typical Evaluation Board measurements

Tbackside = +25°C, Vd = 10, 12, 14, 16, 18 & 20V, Id = 150 mA @25°C; Pin = 12dBm

Id (A) versus Frequency (GHz) with voltage variation



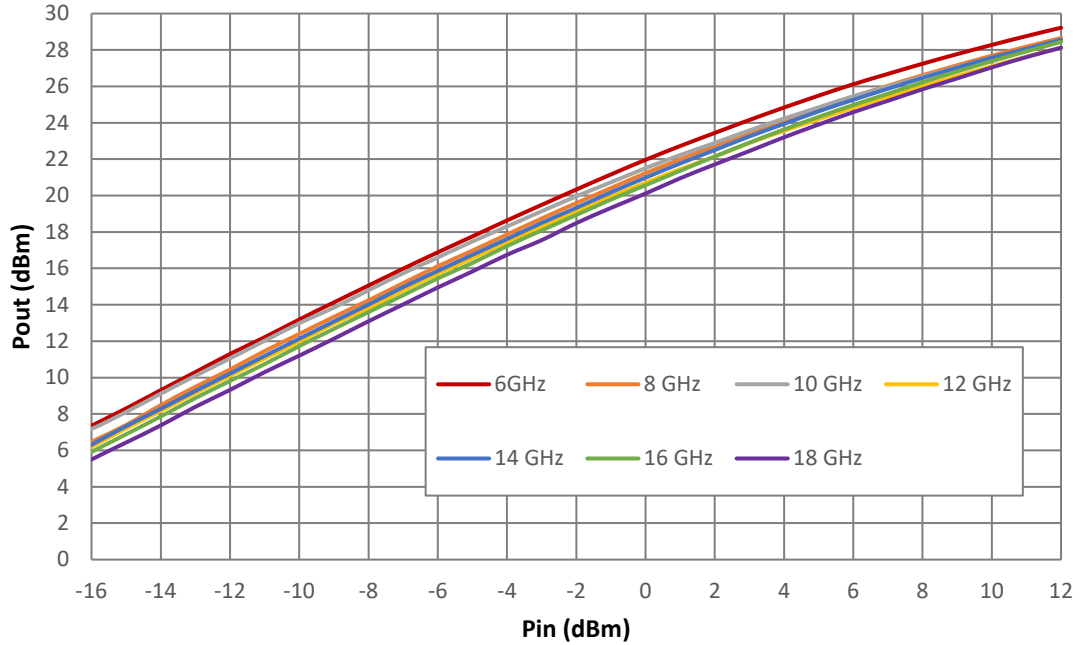
PAE (%) versus Frequency (GHz) with voltage variation



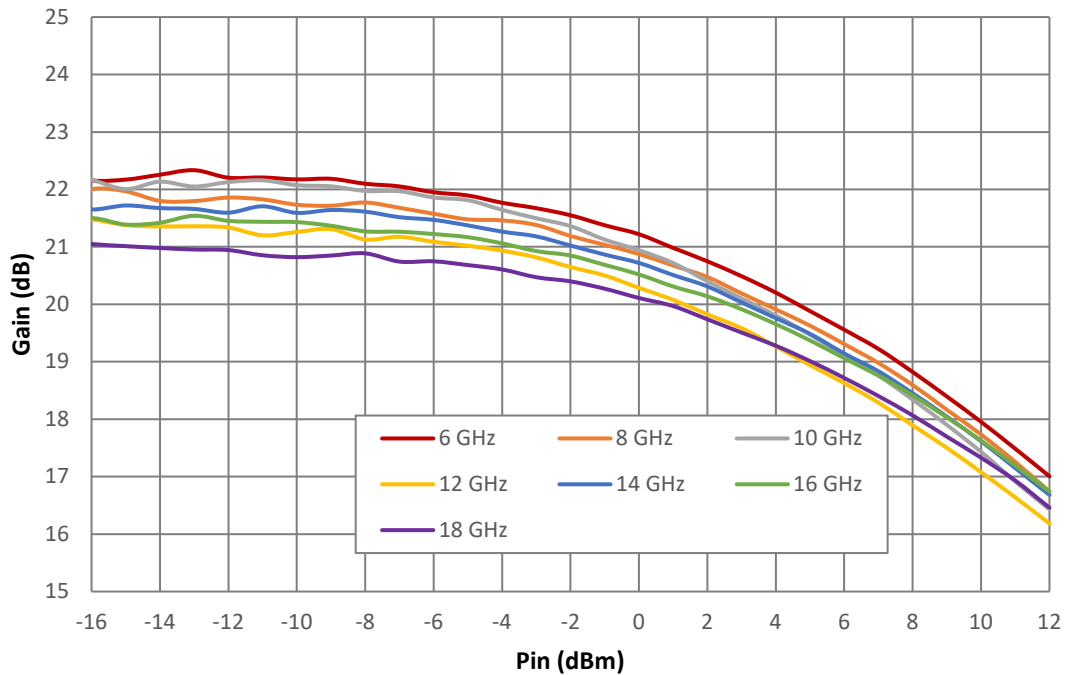
Typical Evaluation Board measurements

Tbackside = +25°C, Vd = +20V, Idq = 150 mA;

Pout (dBm) versus Pin (dBm) with Frequency variation



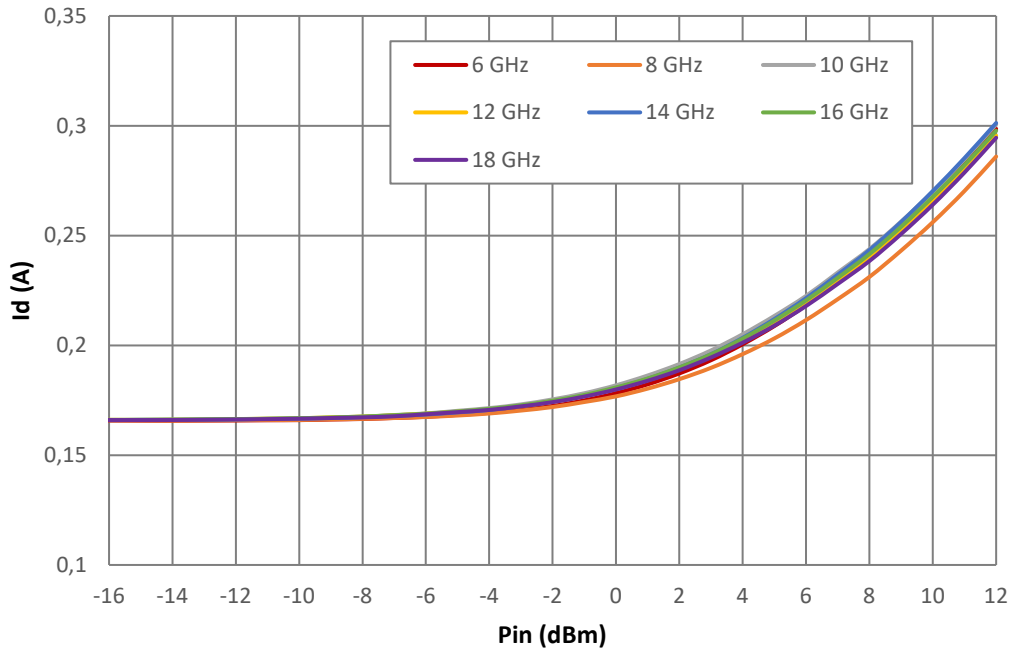
Gain (dB) versus Pin (dBm) with Frequency variation



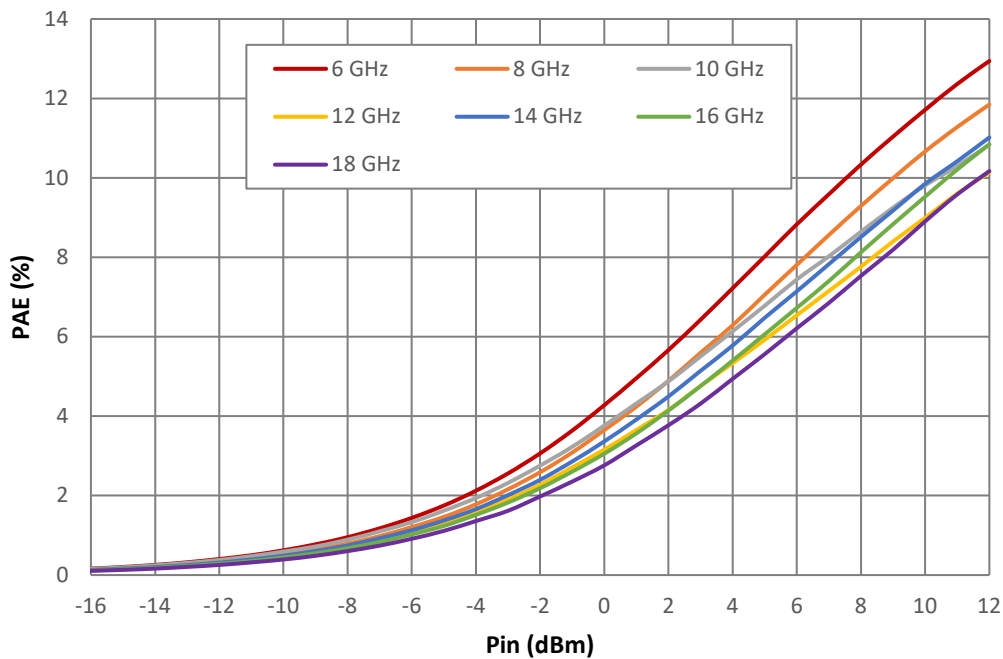
Typical Evaluation Board measurements

Tbackside = +25°C, Vd = +20V, Id = 150 mA

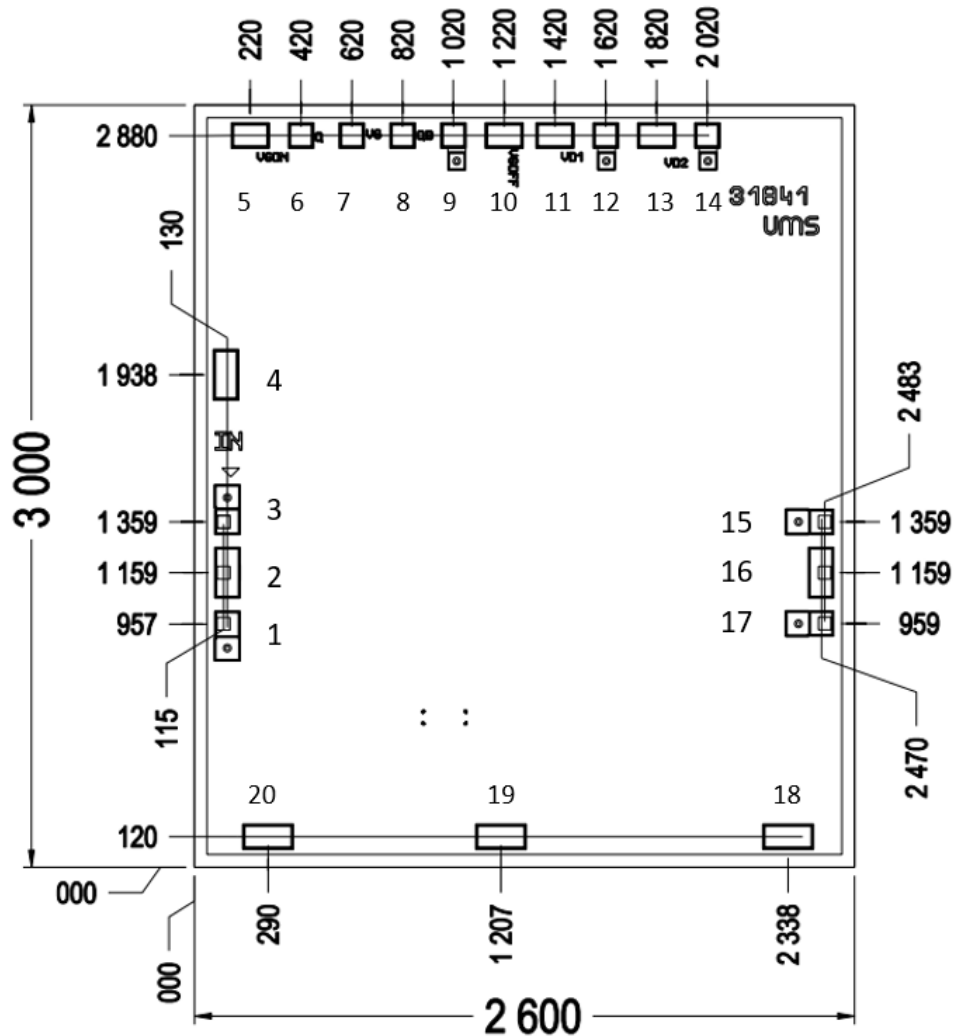
Id (A) versus Pin (dBm) with Frequency variation



PAE (%) versus Pin (dBm) with Frequency variation



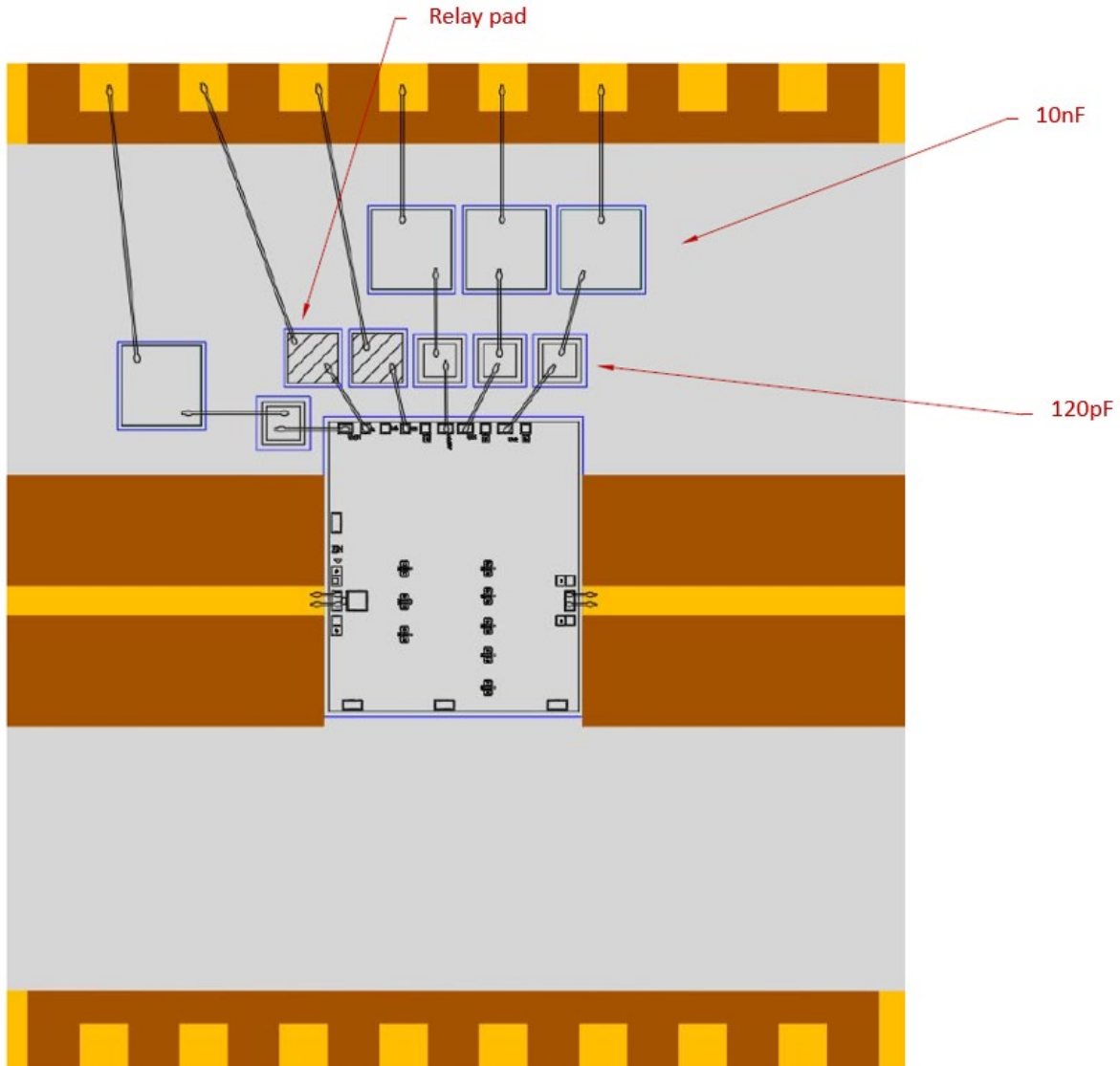
Chip mechanical data



Pad number	Pad name	Pad type	Description
1,3, 15 & 17	GND	RF GND	
9, 12 & 14	GND	DC GND	
2	IN	RF IN	RF input signal
16	OUT	RF OUT	RF output signal
13	VD2	Supply	2 nd stage drain supply
11	VD1	Supply	1 st stage drain supply
10	VGOFF		Gate pinch off voltage
8	QB		Gate control voltage
7	VG	Supply	Gate supply
6	Q		Gate control voltage
5	VGON		Gate bias voltage
4, 18, 19 & 20	-	Not connected	Relay pad

Recommended assembly plan

- Compatible with the proposed footprint.
- Recommended for the implementation of this product on a module board.
- Decoupling capacitors of 120pF, 10nF and 1μF are recommended for all DC accesses.
- See application note AN0030 for details.



Notes



Recommended ESD management

Refer to the application note AN0020 available at <https://www.ums-rf.com> for ESD sensitivity and handling recommendations for the UMS products.

Recommended environmental management

UMS products are compliant with the regulation in particular with the directives RoHS N°2011/65 and REACH N°1907/2006. More environmental data are available in the application note AN0019 also available at <https://www.ums-rf.com>.

Recommended reflow process assembly

Refer to the application note AN0001 available at <https://www.ums-rf.com> for die attach.

Ordering Information

Chip form: CHA5618-99F/00

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